



SDI Review Form 1.6

Journal Name:	Journal of Engineering Research and Reports
Manuscript Number:	Ms_JERR_51011
Title of the Manuscript:	Estimation of Solder Ball Collapse Height in Semiconductor Packaging using Theoretical and Solid Modeling Techniques
Type of the Article	

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)



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PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her
Compulsory REVISION comments		
Minor REVISION comments		
Optional/General comments	<p>Reviewer's comment:</p> <p>Dear Editor:</p> <p>The manuscript focused on the "Estimation of Solder Ball Collapse Height in Semiconductor Packaging using Theoretical and Solid Modeling Techniques", which is new novel and very useful in material fields. It is recommended to accept after major revision. However, some parts need to revise, which are listed below as follows. The main points need to revise before publication.</p> <p>[1] The new relate references are needed to add in the revised manuscript.</p> <p>[2] The authors investigate many parameters in this study. What is optimal condition in this work? Please explain and add it in the revised manuscript.</p> <p>[3] The grammar of English should be written more carefully in the manuscript; English must be checked and improved by Native English speaker.</p> <p>[4] What are the important applications in this study? Please add in the revised manuscript.</p> <p>[5] Theoretical calculations how to set the initial conditions or parameters to get close to the actual situation.</p> <p>[6] Can theoretical calculations and practical applications be compared to each other?</p> <p>[7] What are the important applications in this study? Please add in the revised manuscript.</p> <p>[8] The authors investigate many parameters in this study. What is optimal condition in this work? Please explain and add it in the revised manuscript.</p>	<p>Thanks to the reviewer for the inputs/comments.</p> <p>Refer to items highlighted in yellow in the revision.</p> <ul style="list-style-type: none"> • Additional references added. • Added and highlighted in the revision. Based on customer requirement: The optimal condition is the solder ball size needed to meet the target solder ball height of 100µm. • The initial condition is just set at an arbitray value and when Excel's solver macro performs the iterative process, it still converges to the correct solution. But it could also be based on prior experience estimate or using preliminary CAD estimation 1st. • Yes, theoretical calculations are compared with result in actual application (actual solder ball height measurement). • Important applications – semiconductor packaging specifically BGA package design and development, mobile devices/sensors. • The theoretical setting conditions are selected based on actual customer requirement or need (100µm solder ball collapse height). • Resolution of figures now improved for clarity/visibility.

PART 2:

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	<i>(If yes, Kindly please write down the ethical issues here in details)</i>	